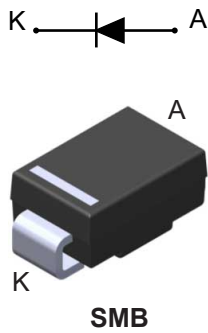




# THE DATASHEET OF STPS2L25U



## 25 V power Schottky rectifier



### Features

- Very low forward voltage drop for less power dissipation
- Optimized conduction/reverse losses trade-off which means the highest efficiency in the applications
- Avalanche rated
- ECOPACK<sup>®</sup>2 compliant

### Applications

- Cordless appliance
- SSD
- Battery charger
- Telecom power
- DC / DC converter

### Description

Schottky rectifiers designed for high frequency miniature switched mode power supplies such as adaptors and on board DC/DC converters.

Packaged in SMB for thermal resistance characteristic improvement, the [STPS2L25](#) is ideal for use in parallel with MOSFETs in synchronous rectification.

Product status	
STPS2L25	
Product summary	
Symbol	Value
$I_{F(AV)}$	2 A
$V_{RRM}$	25 V
$T_{j(max.)}$	150 °C
$V_{F(typ.)}$	0.325 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	25	V
$I_{F(RMS)}$	Forward rms current	10	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$ square wave	$T_L = 125\text{ °C}$	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}$ , $T_j = 125\text{ °C}$	W
$T_{stg}$	Storage temperature range	-65 to +150	°C
$T_j$	Maximum operating junction temperature <sup>(1)</sup>	+150	°C

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameter**

Symbol	Parameter	Max. value	Unit
$R_{th(j-l)}$	Junction to lead	25	°C/W

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	90	$\mu\text{A}$
		$T_j = 125\text{ °C}$		-	15	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 2\text{ A}$	-	0.450	V
		$T_j = 125\text{ °C}$		-	0.325	
		$T_j = 25\text{ °C}$	$I_F = 4\text{ A}$	-	0.530	
		$T_j = 125\text{ °C}$		-	0.430	

1. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

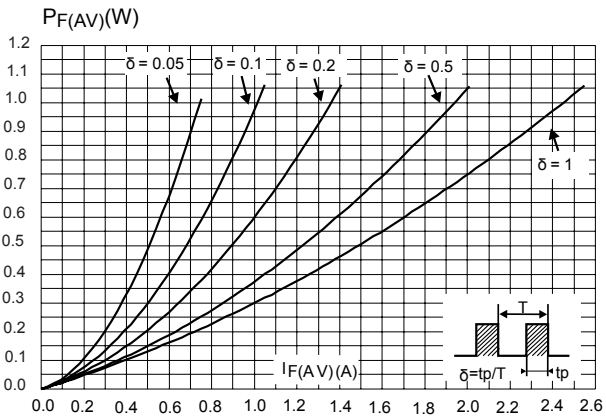
$$P = 0.24 \times I_{F(AV)} + 0.068 \times I_{F(RMS)}^2$$

For more information, please refer to the following application notes related to the power losses :

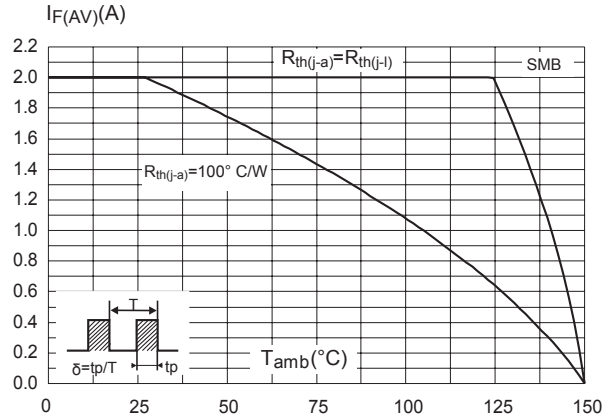
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

### 1.1 Characteristics (curves)

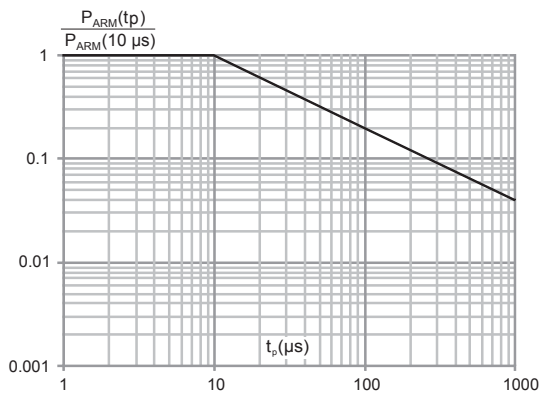
**Figure 1. Average forward power dissipation versus average forward current**



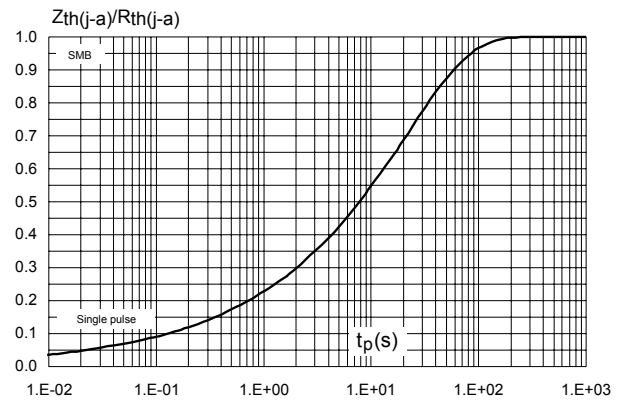
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**

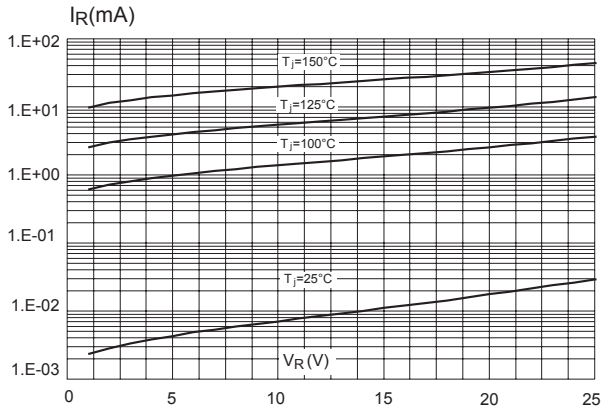
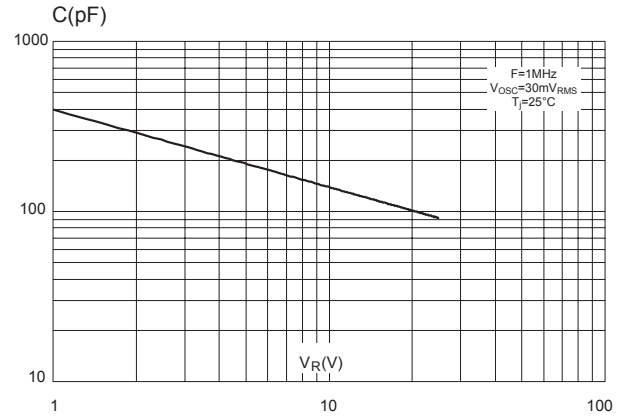
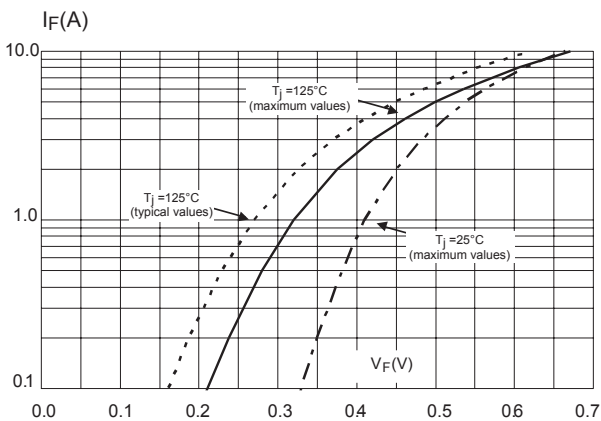
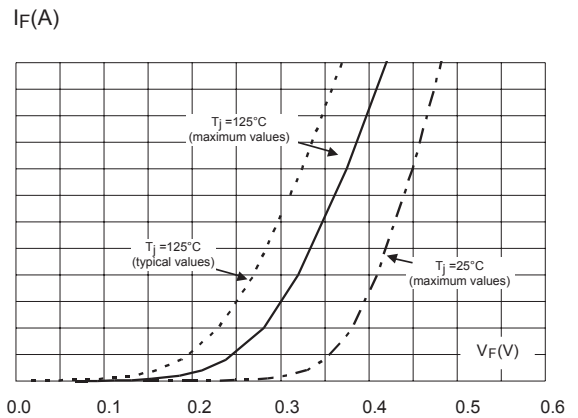
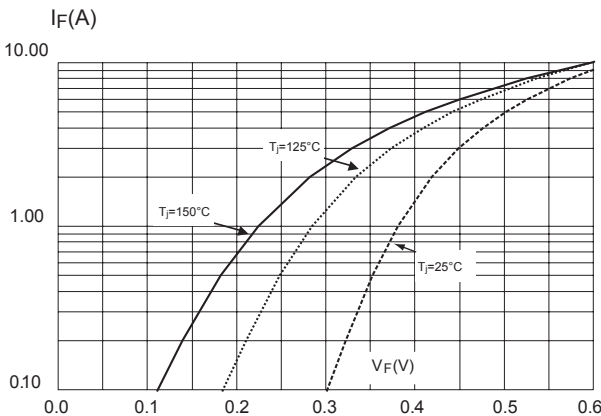
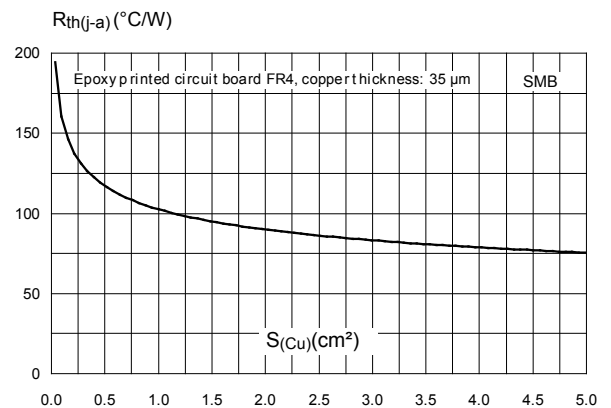


**Figure 3. Normalized avalanche power derating versus junction temperature ( $T_j = 125^{\circ}C$ )**



**Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration**



**Figure 5. Reverse leakage current versus reverse voltage applied (typical values)**

**Figure 6. Junction capacitance versus reverse voltage applied (typical values)**

**Figure 7. Forward voltage drop versus forward current (high level)**

**Figure 8. Forward voltage drop versus forward current (low level)**

**Figure 9. Forward voltage drop versus forward current (typical values)**

**Figure 10. Thermal resistance junction to ambient versus copper surface area under each lead**


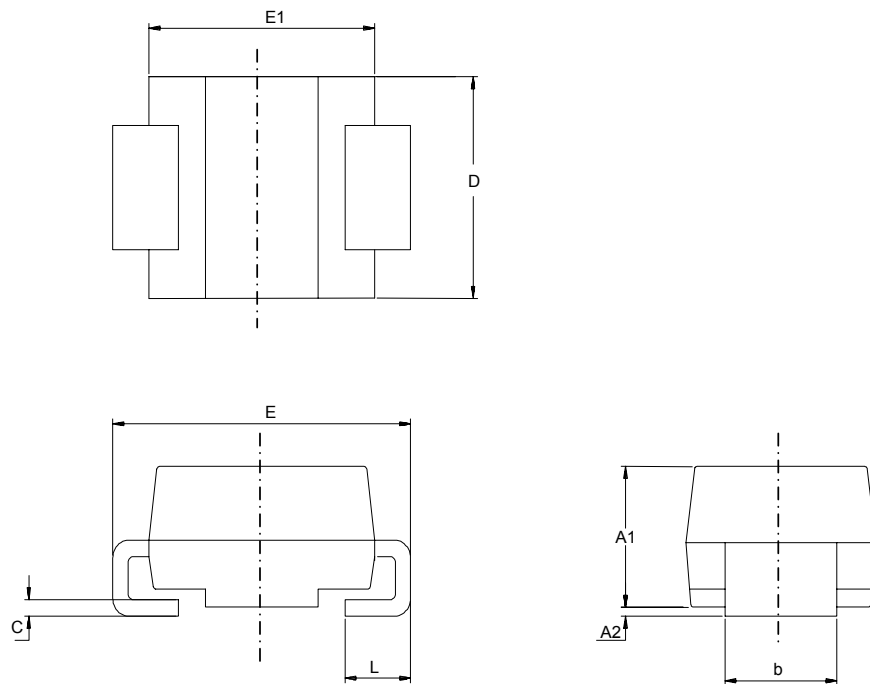
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 SMB package information

- Epoxy meets UL94, V0
- Lead-free package

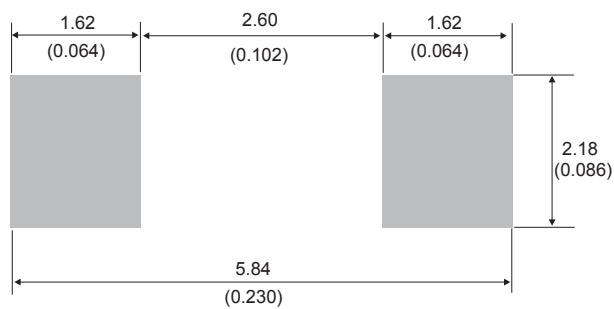
**Figure 11. SMB package outline**



**Table 4. SMB package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.0748	0.0965
A2	0.05	0.20	0.0020	0.0079
b	1.95	2.20	0.0768	0.0867
c	0.15	0.40	0.0059	0.0157
D	3.30	3.95	0.1299	0.1556
E	5.10	5.60	0.2008	0.2205
E1	4.05	4.60	0.1594	0.1811
L	0.75	1.50	0.0295	0.0591

**Figure 12. SMB recommended footprint**



### 3 Ordering information

**Table 5. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS2L25U	G23	SMB	0.107 g	2500	Tape and reel

## Revision history

**Table 6. Document revision history**

Date	Version	Changes
Jul-2003	4A	Last update.
08-Feb-2007	5	Reformatted to current standard. Added ECOPACK statement. Added SMB flat package.
09-Oct-2018	6	Updated <a href="#">Table 1</a> . Absolute ratings (limiting values at 25 °C, unless otherwise specified) and <a href="#">Figure 3</a> . Normalized avalanche power derating versus junction temperature ( $T_j = 125\text{ °C}$ ). Removed SMB flat package.

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